

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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3mm Three Position CBI Housing

#### **Features**

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- $\bullet$  Reliable & robust
- Custom color combinations available
- RoHS Compliant





#### Package Schematics 4.32(0.17) 2.62(0.103) 11.43(0.45) ø2.9(0.114) LED1 5.08 3.42(0.135) 15.24(0.6) 7.14(0.281) LEDS 5.08 4.84(0.191) ED3 3.5(0.138)Min. 0.7Max $\Box 0.5(0.02)^{+}_{-}$ Cathode Top LED 4.45(0.175) 2.54(0.1) 2.54(0.1) 2.54(0.1) Recommended PCB Layout

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		Red (GaAsP/GaP)	Unit		
Reverse Voltage	$V_{\mathrm{R}}$	5	V		
Forward Current	$I_{\mathrm{F}}$	30	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\mathrm{FS}}$	160	mA		
Power Dissipation	$P_{D}$	75	mW		
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C		
Storage Temperature	Tstg	-40 ~ +85			
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

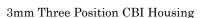
A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T <sub>A</sub> =25°C)		Red (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	$V_{\mathrm{F}}$	1.9	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	$V_{\mathrm{F}}$	2.5	V
Reverse Current (Max.) $(V_R=5V)$	$I_R$	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λР	627*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λD	617*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	Δλ	45	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	15	pF

4.45(0.175)2.54(0.1)x2PL

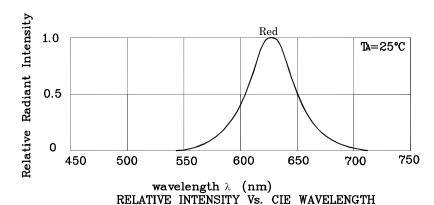
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} \text{Luminous Intensity} \\ \text{CIE127-2007*} \\ \text{(I_F=10mA)} \\ \text{mcd} \end{array}$		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XPZ3LUR11D	Red	GaAsP/GaP	Red Diffused	12 10*	29 19*	627*	50°

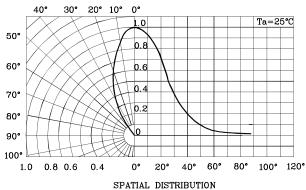
<sup>\*</sup>Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



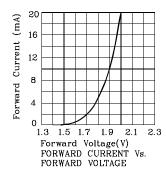


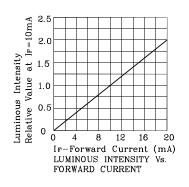


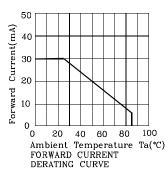


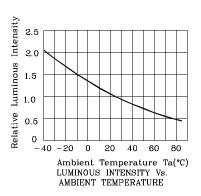


#### ❖ Red

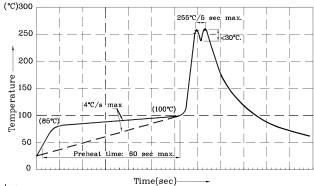








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

- Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of  $260^{\circ}C$  2. Peak wave soldering temperature between  $245^{\circ}C \sim 255^{\circ}C$  for 3 sec
- 3.Do not apply stress to the epoxy resin while the temperature is above  $85\,^\circ\text{C}.$  4.Fixtures should not incur stress on the component when mounting and
- during soldering process. 5.SAC 305 solder alloy is recommended.
- 6. No more than one wave soldering pass

## Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

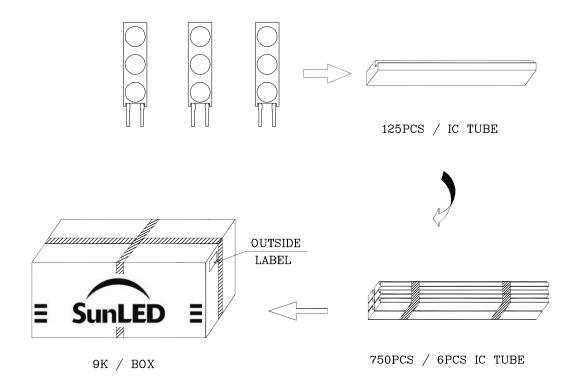
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

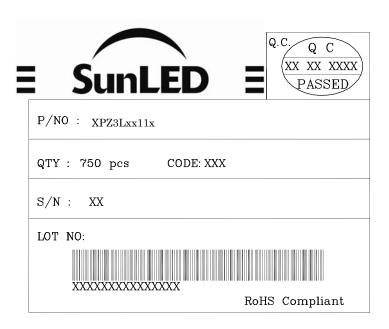
Note: Accuracy may depend on the sorting parameters.





### PACKING & LABEL SPECIFICATIONS





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- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
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Oct 10,2016

XDSB8829 V1-X Layout: Maggie L.